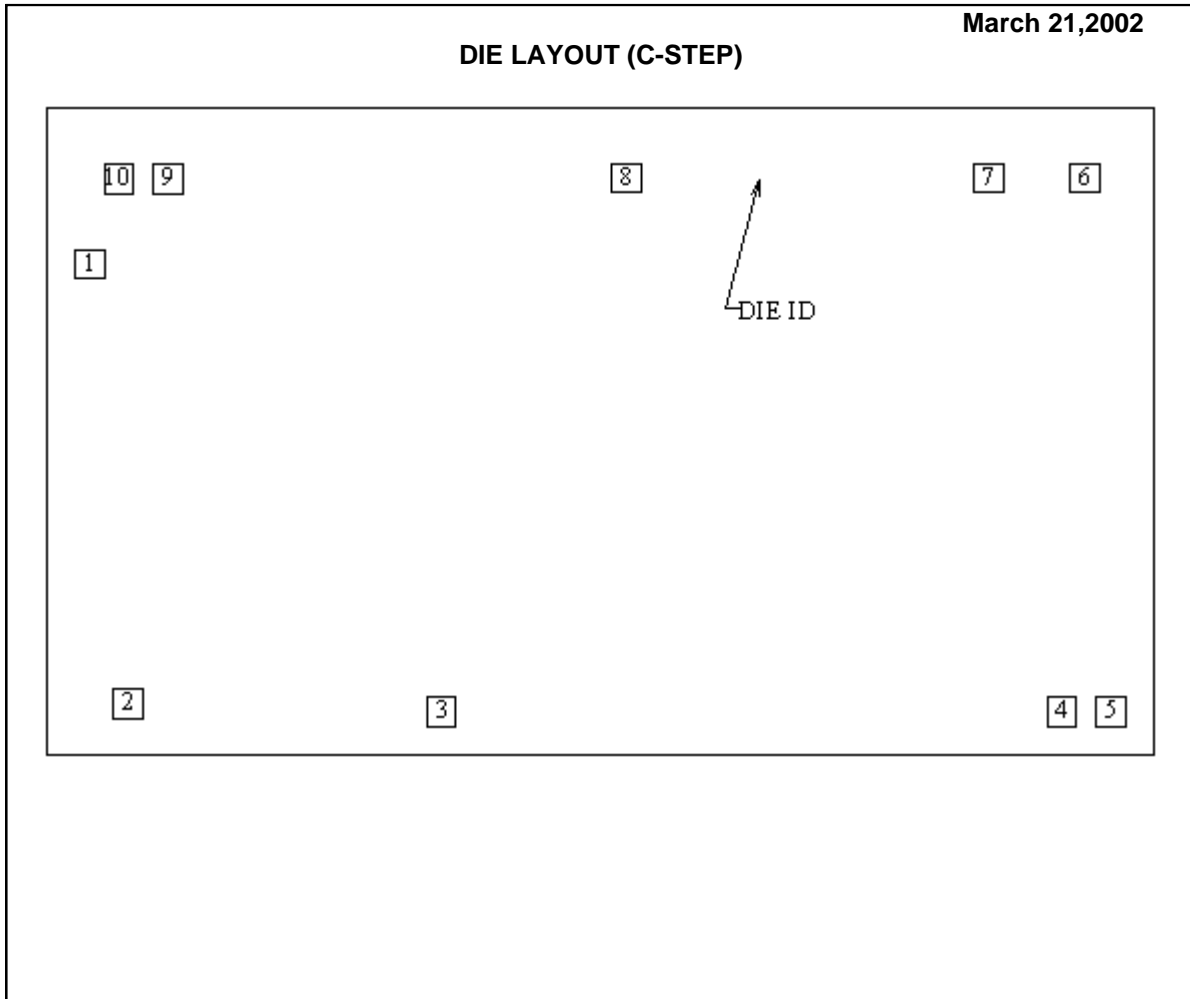


LM6172 MDC MWC
DUAL HIGH SPEED, LOW POWER, LOW DISTORTION VOLTAGE FEEDBACK AMPLIFIERS



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM6172C	Bond Pad Opening Size (min)	80μm x 80μm
Die Step	C	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1778μm x 3048μm 70mils x 120mils	Back Side Connection	Floating
Thickness	330μm Nominal		
Min Pitch	134μm Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (C -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection						
SIGNAL NAME	PAD# NUMBER	X/Y COORDINATES		PAD SIZE		
		X	Y	X	Y	
OUTPUT A	1	-1406	461	80	x	80
INPUT A-	2	-1301	-750	80	x	80
INPUT A+	3	-437	-771	80	x	80
V-	4	1271	-771	80	x	80
V-	5	1406	-771	80	x	80
INPUT B+	6	1333	698	80	x	80
INPUT B-	7	1068	698	80	x	80
OUTPUT B	8	71	698	80	x	80
V+	9	-1191	695	80	x	80
V+	10	-1326	695	80	x	80

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